same sky

MODEL: HSS04-B20-P318 | DESCRIPTION: HEAT SINK

FEATURES

- TO-220 package
- solder pin
- aluminum alloy
- black anodized finish

RoHS

MODEL

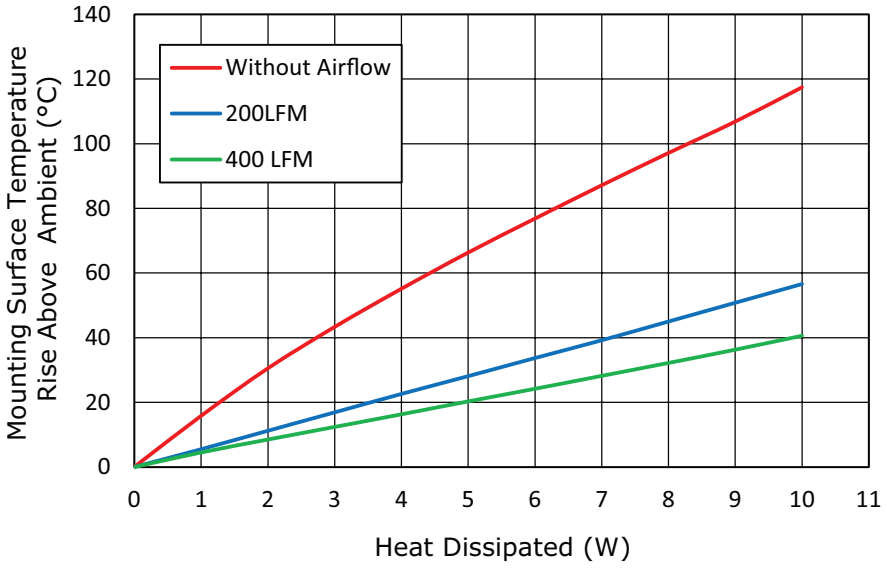
MODEL	thermal resistance[1]				power dissipation[1]
	@ 75°C ΔT, nat conv (°C/W)	@ 1 W, nat conv (°C/W)	@ 1 W, 200 LFM (°C/W)	@ 1 W, 400 LFM (°C/W)	@ 75°C ΔT, nat conv (W)
HSS04-B20-P318	12.79	15.8	5.5	4.5	5.86

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

	Heatsink Temperature Rise Above Ambient (ΔT = Ths - Ta) (°C)		
Power (W)	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	15.8	5.5	4.5
2	30.5	11.2	8.5
3	43.3	16.9	12.4
4	55.1	22.6	16.3
5	66.3	28.1	20.3
6	76.8	33.7	24.2
7	87.1	39.2	28.2
8	97.1	45.0	32.2
9	106.8	50.8	36.3
10	117.4	56.6	40.6

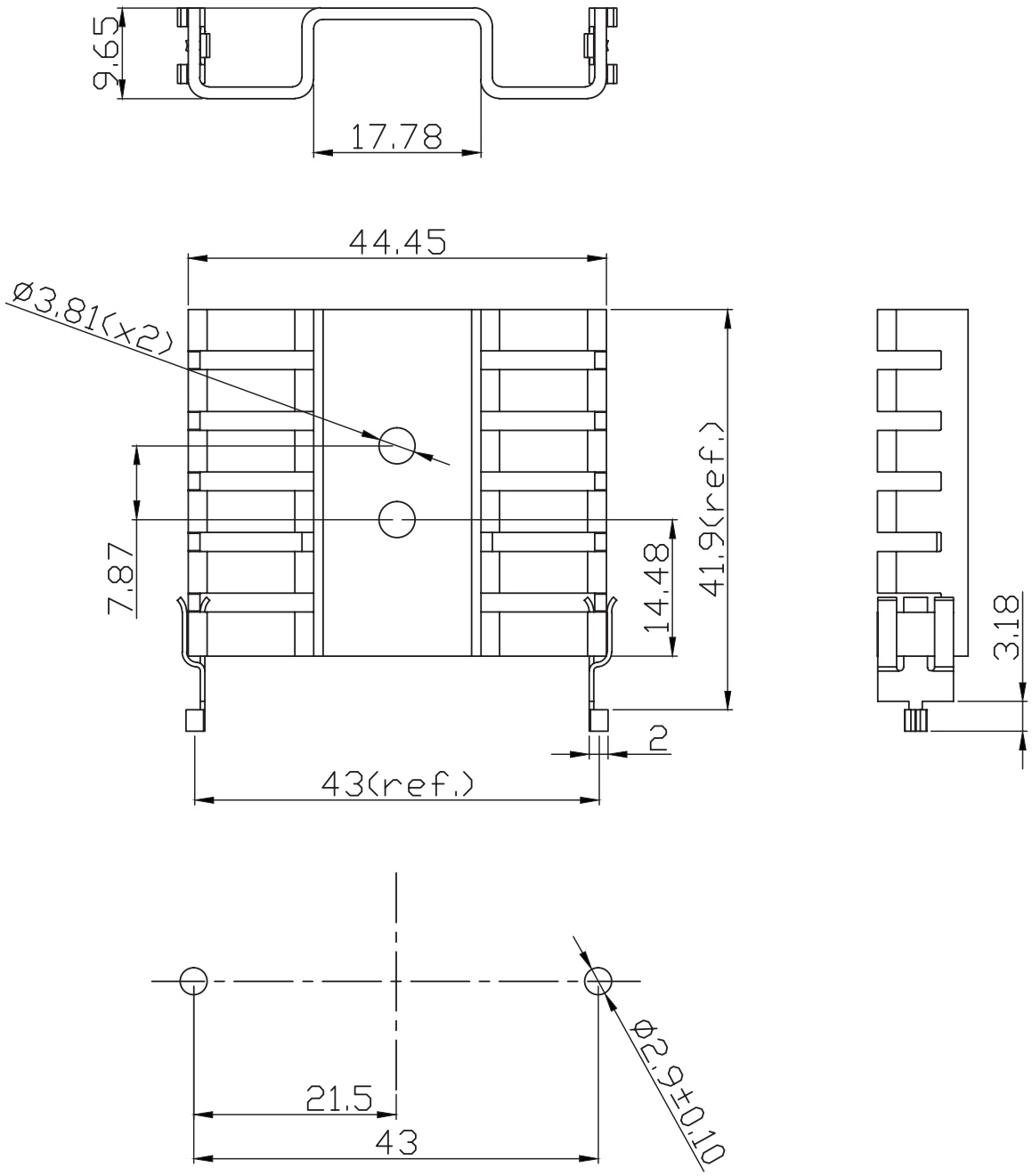
Ths: "hot spot" temperature measured on the heatsink
Ta: ambient temperature



MECHANICAL DRAWING

units: mm
tolerance: ±0.3 mm

MATERIAL	AL 1050
FINISH	black anodized
THICKNESS	1.2 mm
PIN MATERIAL	phosphor bronze
PIN PLATING	2~3 μm tin
WEIGHT	8.0 g



Recommended PCB Layout
Top View

REVISION HISTORY

rev.	description	date
1.0	initial release	06/25/2021
1.01	logo, datasheet style update	08/05/2022
1.02	CUI Devices rebranded to Same Sky	09/12/2024
1.03	added recommended PCB layout	11/14/2025

The revision history provided is for informational purposes only and is believed to be accurate.